Silicon N-Channel MOS FET

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Application

Low frequency power amplifier

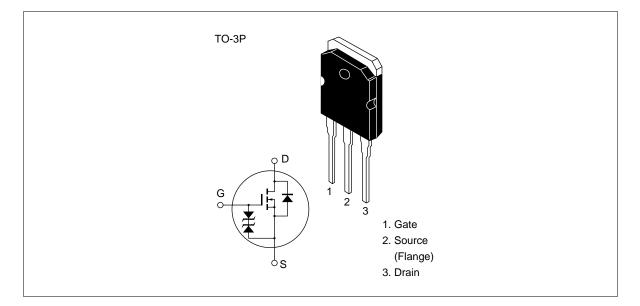
Complementary pair with 2SJ160, 2SJ161 and 2SJ162

Features

- Good frequency characteristic
- High speed switching
- Wide area of safe operation
- Enhancement-mode
- Good complementary characteristics
- Equipped with gate protection diodes
- Suitable for audio power amplifier



Outline



Absolute Maximum Ratings (Ta = 25°C)

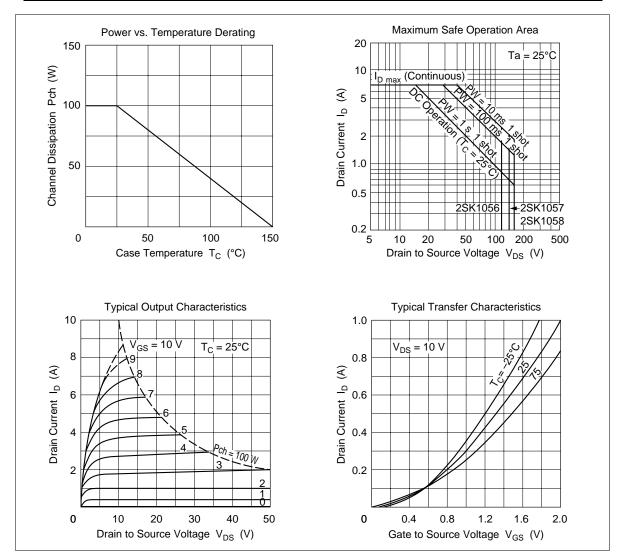
Item		Symbol	Ratings	Unit
Drain to source voltage	2SK1056	V _{DSX}	120	V
	2SK1057		140	
	2SK1058		160	
Gate to source voltage		V _{GSS}	±15	V
Drain current		I _D	7	А
Body to drain diode reverse drain current		I _{DR}	7	А
Channel dissipation		Pch*1	100	W
Channel temperature		Tch	150	°C
Storage temperature		Tstg	-55 to +150	°C

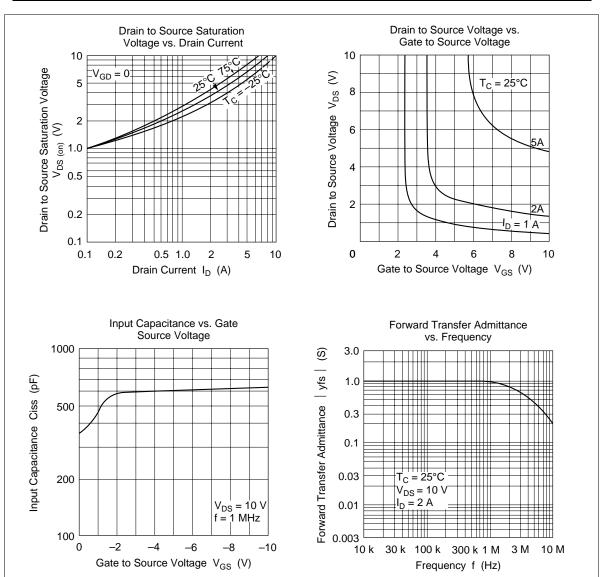
Note: 1. Value at $T_c = 25^{\circ}C$

Electrical Characteristics (Ta = 25°C)

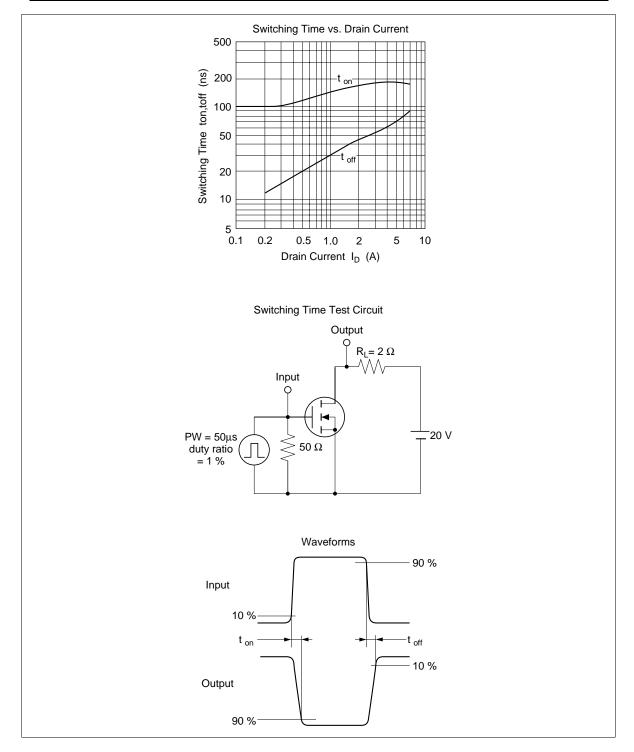
Item		Symbol	Min	Тур	Max	Unit	Test conditions
Drain to source	2SK1056	$V_{(BR)DSX}$	120	—	_	V	$I_{\rm D} = 10 \text{ mA}, V_{\rm GS} = -10 \text{ V}$
breakdown voltage	2SK1057	_	140				
	2SK1058	_	160				
Gate to source breakdown voltage		$V_{(\text{BR})\text{GSS}}$	±15	—	—	V	$I_{G} = \pm 100 \ \mu A, \ V_{DS} = 0$
Gate to source cutoff voltage		$V_{\text{GS(off)}}$	0.15	_	1.45	V	$I_{\rm D}$ = 100 mA, $V_{\rm DS}$ = 10 V
		$V_{\text{DS(sat)}}$	_	—	12	V	$I_{D} = 7 \text{ A}, \text{ V}_{GD} = 0 * 1$
Forward transfer admittance		yfs	0.7	1.0	1.4	S	$I_{\rm D} = 3$ A, $V_{\rm DS} = 10$ V * ¹
Input capacitance		Ciss	_	600	_	pF	$V_{GS} = -5 V, V_{DS} = 10 V,$
Output capacitance		Coss	_	350	_	pF	f = 1 MHz
Reverse transfer capacitance		Crss		10	_	pF	
Turn-on time		t _{on}		180	_	ns	$V_{DD} = 20 \text{ V}, \text{ I}_{D} = 4 \text{ A},$
Turn-off time		t _{off}	_	60	—	ns	

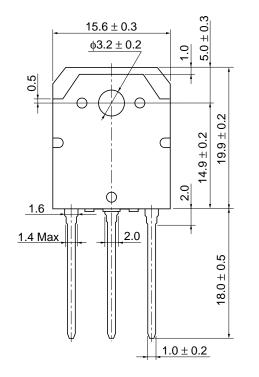
Note: 1. Pulse test

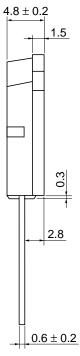




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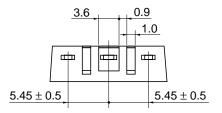








Unit: mm



Hitachi Code	TO-3P
JEDEC	—
EIAJ	Conforms
Weight (reference value)	5.0 g

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